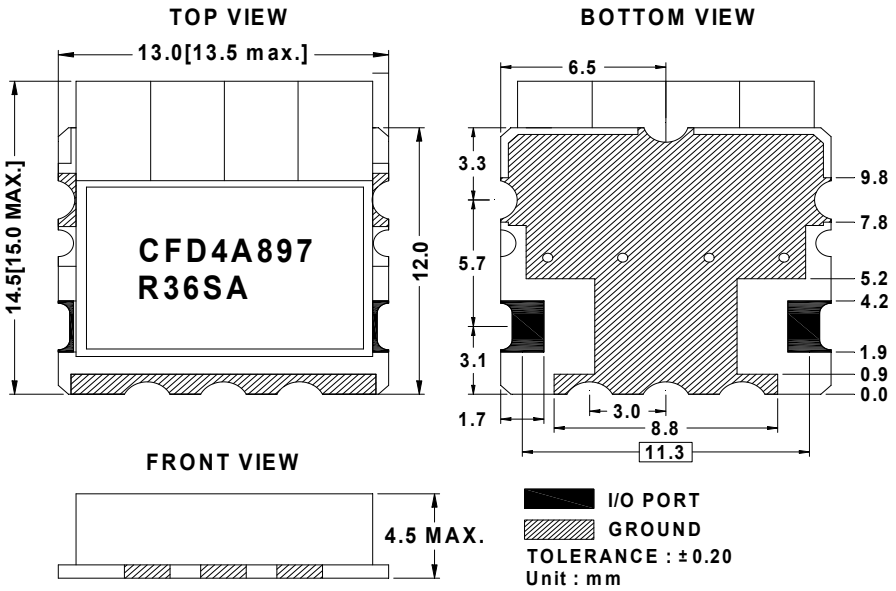
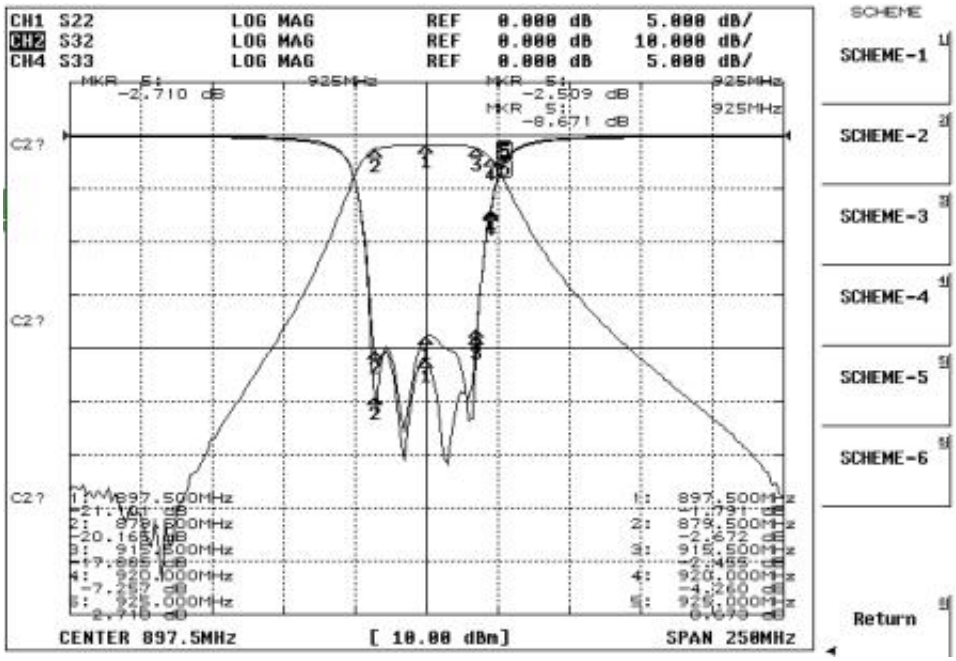
Electrical Specification

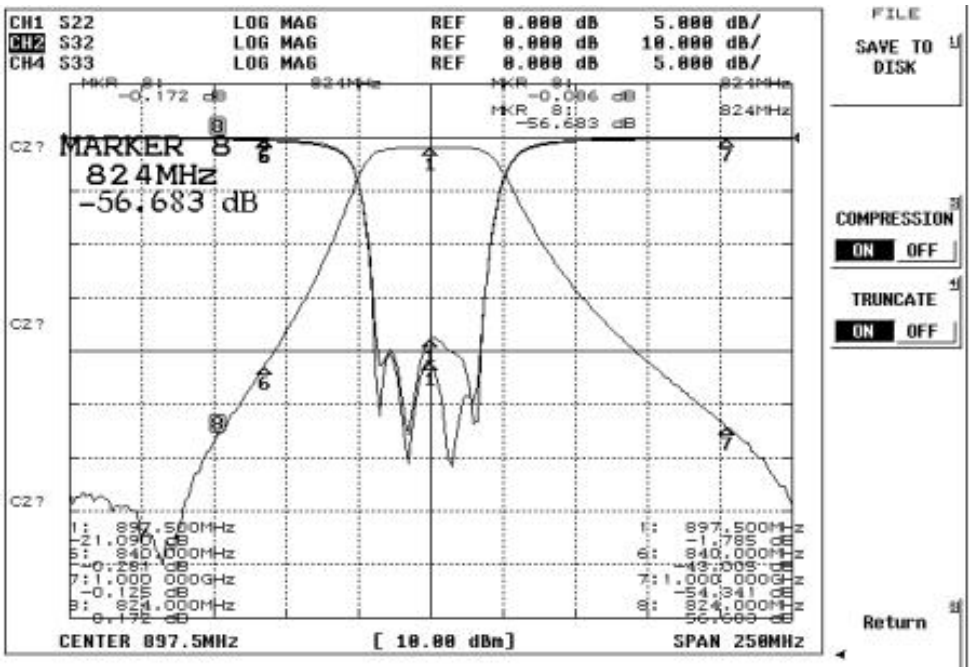
ITEMS	SPEC	UNIT
Center Frequency [fo]	897.5	MHz
Bandwidth [BW]	fo ±18 [879.5~915.5]	MHz
Insertion Loss in BW	3.0	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation ☐ Absolute Value ☑ Relative Value	43.0 dBc min. @ fo ± [300.0 ~ 824.0]	MHz
	34.0 dBc min. @ fo ± [840.0 &]	MHz
	2.0 dBc min. @ fo ± [920 &]	MHz
	6.0 dBc min. @ fo ± [925 &]	MHz
	30.0 dBc min. @ fo ± [1000 ~ 2000]	MHz
	dBc min. @ fo ± [& 3000.0]	MHz
Group Delay Variation		ns max
Input Power	2	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

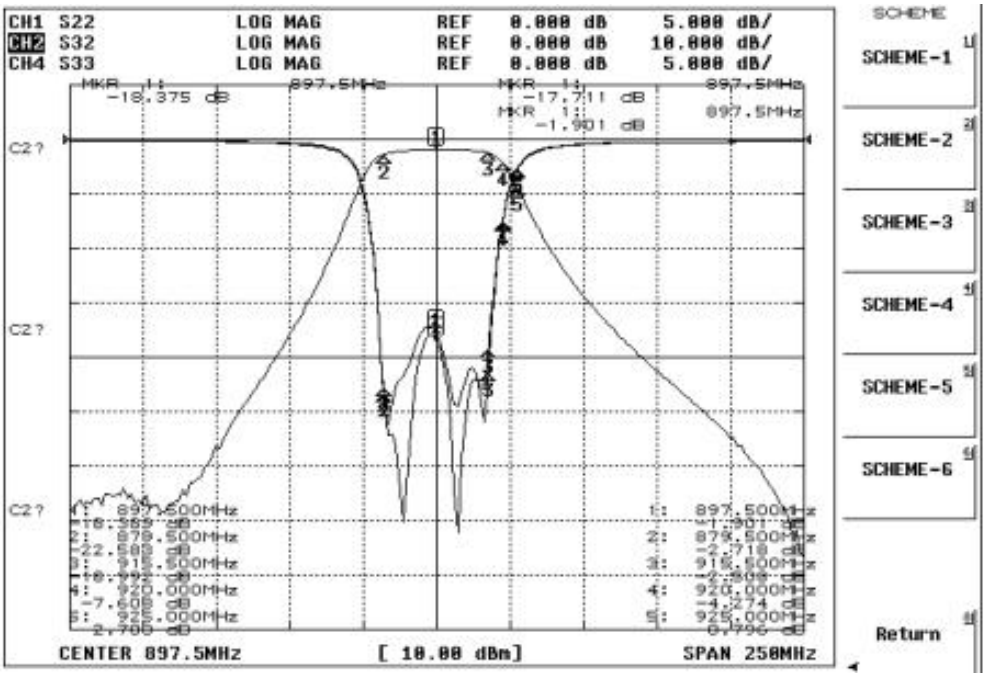
Mechanical Specification

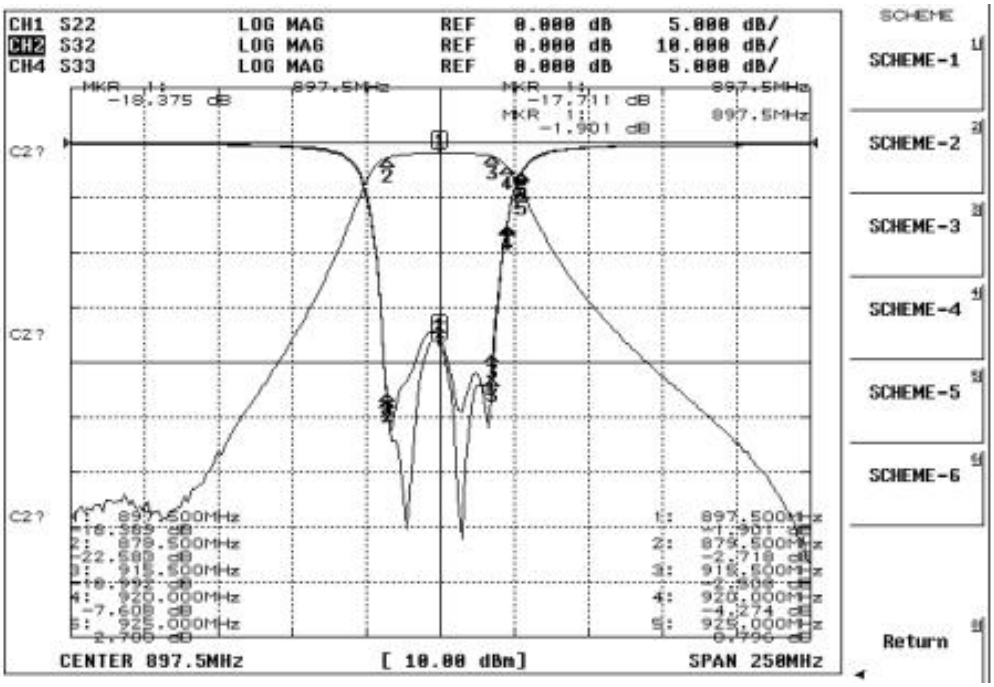


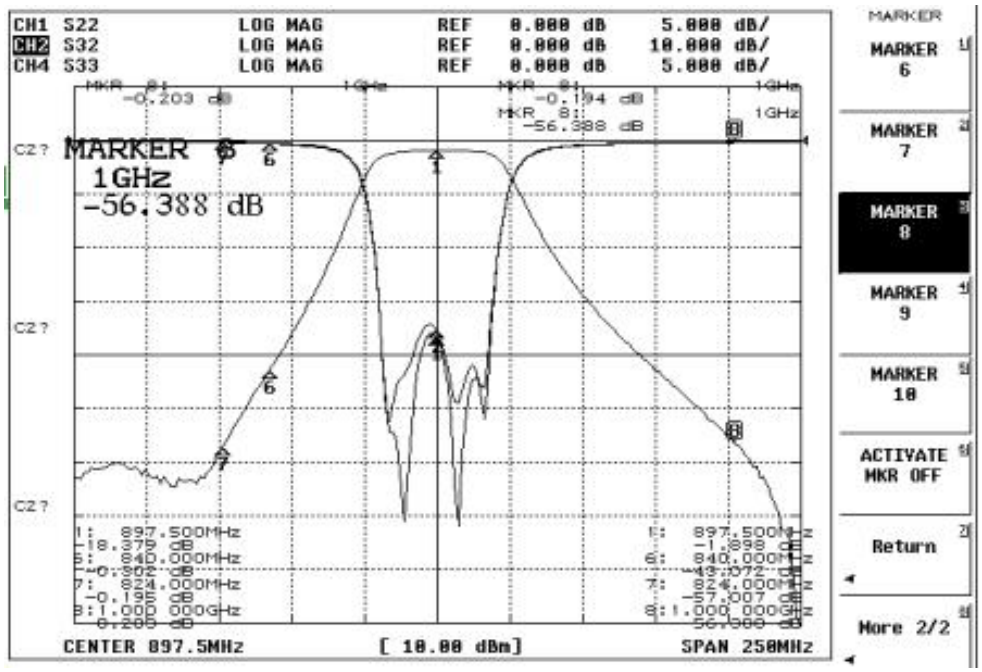
Plot Data

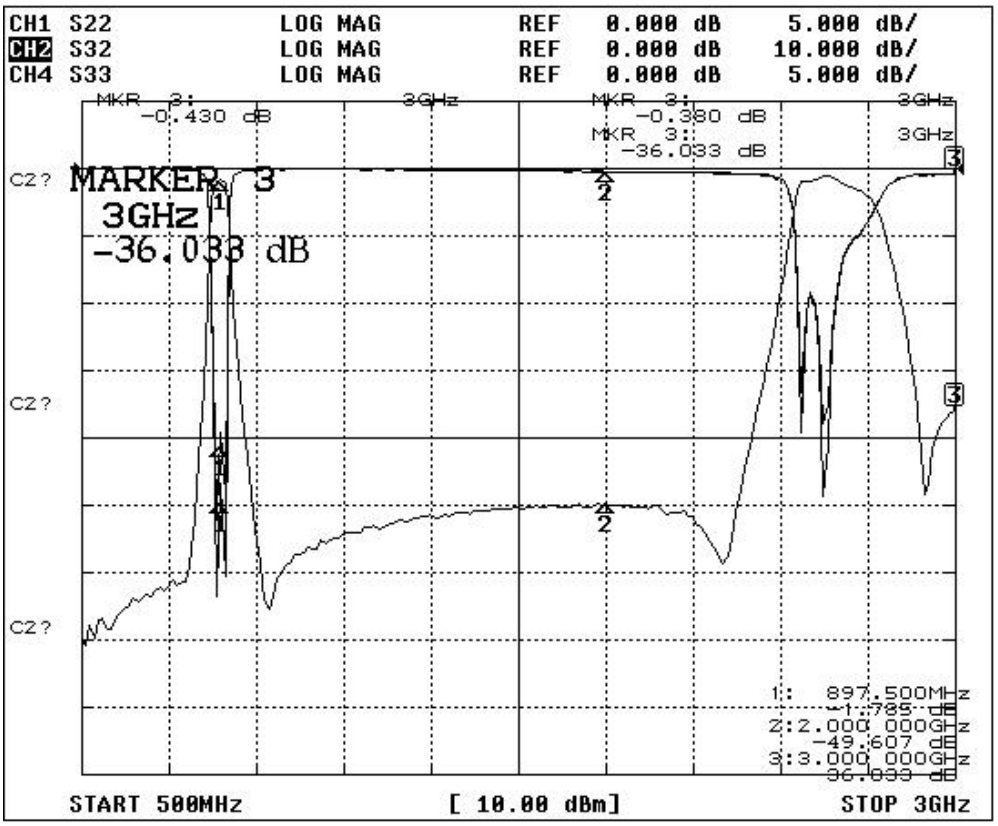

CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/
CENTER 897.5MHz
[10.00 dBm]
SPAN 250MHz
SCHEME
SCHEME-1
SCHEME-2
SCHEME-3
SCHEME-4
SCHEME-5
SCHEME-6
Return


CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/
MARKER 8
824MHz
-56.683 dB
CENTER 897.5MHz
[10.00 dBm]
SPAN 250MHz
FILE
SAVE TO DISK
COMPRESSION
ON OFF
TRUNCATE
ON OFF
Return

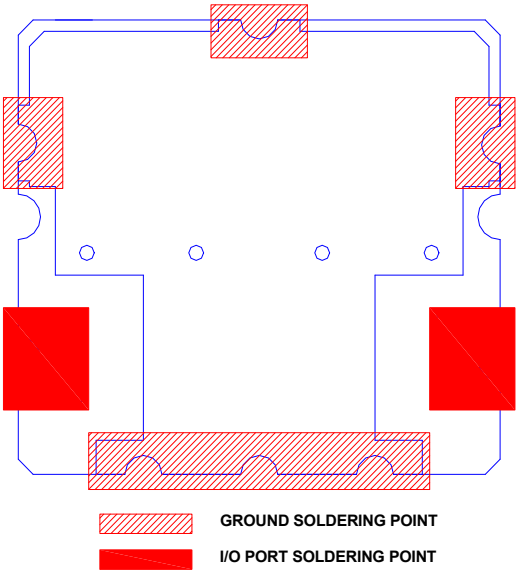

CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/
CENTER 897.5MHz
[10.00 dBm]
SPAN 250MHz
SCHEME
SCHEME-1
SCHEME-2
SCHEME-3
SCHEME-4
SCHEME-5
SCHEME-6
Return


CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/
CENTER 897.5MHz
[10.00 dBm]
SPAN 250MHz
SCHEME
SCHEME-1
SCHEME-2
SCHEME-3
SCHEME-4
SCHEME-5
SCHEME-6
Return

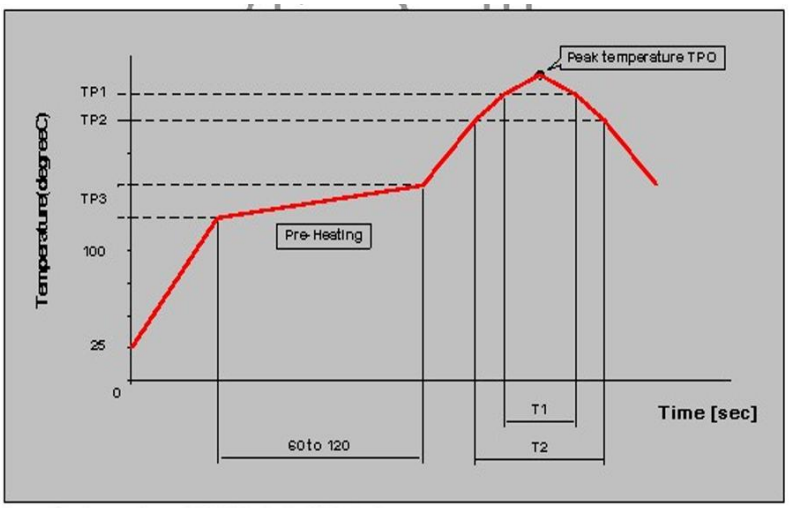

CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/
MARKER 8
1GHz
-56.388 dB
CENTER 897.5MHz
[10.00 dBm]
SPAN 250MHz
MARKER
MARKER 6
MARKER 7
MARKER 8
MARKER 9
MARKER 10
ACTIVATE MKR OFF
Return
More 2/2


CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/
MARKER 3
3GHz
-36.033 dB
1: 897.500MHz
2:2.000 000GHz
-49.607 dB
3:3.000 000GHz
START 500MHz
[10.00 dBm]
STOP 3GHz

Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180